

N And P-Channel Enhancement Mode MOSFET

Description

The PECN4606 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

General Features

◆ N-channel:

 $V_{DS} = 30V, ID = 6.9A$ $R_{DS(ON)} = 13.5m\Omega$ (typical) @ $VGS = 10V$ $R_{DS(ON)} = 17.5m\Omega$ (typical) @ $VGS = 4.5V$

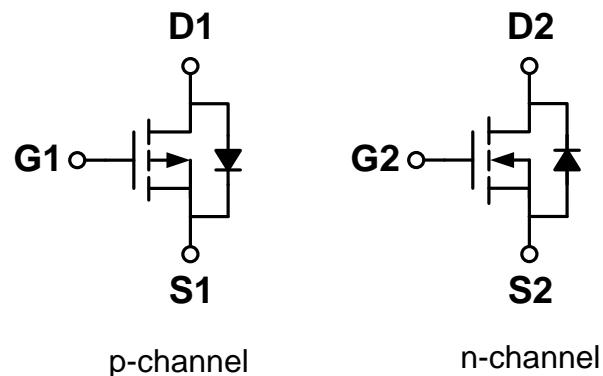
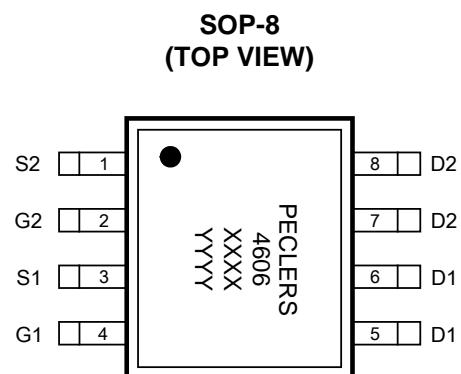
P-Channel:

 $V_{DS} = -30V, ID = -6A$ $R_{DS(ON)} = 35m\Omega$ (typical) @ $VGS = -10V$ $R_{DS(ON)} = 49m\Omega$ (typical) @ $VGS = -4.5V$

- ◆ Excellent gate charge x $R_{DS(ON)}$ product(FOM)
- ◆ Very low on-resistance $R_{DS(ON)}$
- ◆ 150 °C operating temperature
- ◆ Pb-free lead plating
- ◆ 100% UIS tested

Application*100% UIS TESTED!**100% ΔVds TESTED!*

- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification

Schematic diagram**Marking and pin assignment**

Note: XXXX is the date code , YYYY is the Quality Code

Package

SOP-8

**Ordering Information**

Part Number	Storage Temperature	Package	Devices Per Reel
PECN4606SR	-55°C to +150°C	SOP-8	3000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit		Unit
		N	P	
Drain-source voltage	V_{DS}	30	-30	V
Gate-source voltage	V_{GS}	± 20	± 20	V
Maximum power dissipation	P_D	2.0	2.0	W

Operating junction Temperature range		T _j	-55—150	-55—150	°C
Drain Current-Continuous (Silicon Limited)	T _A =25°C	I _D	6	-6	A
	T _A =75°C		5	-5	
Pulsed Drain Current (Package Limited)		I _{DM}	30	-30	A
Avalanche Current ^C		I _{AS} , I _{AR}	10	23	A
Avalanche energy L=0.1mH ^C		E _{AS} , E _{AR}	5	26	mJ
Power Dissipation ^B	T _A =25°C	P _D	2	2	W
	T _A =75°C		1.3	1.3	
Junction and Storage Temperature Range		T _J , T _{STG}	-55—150		°C

N-Channel Electrical Characteristics (T_j=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	30	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =30V, V _{GS} =0V	-	-	1	μA
Gate-body leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
ON Characteristics						
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.0	1.55	3.0	V
Drain-source on-state resistance	R _{DS(ON)}	V _{GS} =10V, I _D =6A	-	13.5	20	mΩ
		V _{GS} =4.5V, I _D =5A	-	17.2	28	
Forward transconductance	g _f	V _{DS} =5V, I _D =6A	-	15	-	S
Dynamic Characteristics						
Input capacitance	C _{ISS}	V _{DS} =15V ,V _{GS} =0V f=1.0MHz	-	255	310	pF
Output capacitance	C _{OSS}		-	45	60	
Reverse transfer capacitance	C _{RSS}		-	35	50	
Gate resistance	R _g	V _{GS} =0V, V _{DS} =0V, f=1.0MHz	-	3.3	4.9	Ω
Switching Characteristics						
Turn-on delay time	t _{D(ON)}	V _{DS} =15V V _{GS} =10V R _L =2.5Ω R _{GEN} =3Ω	-	4.5	-	ns
Rise time	t _r		-	2.5	-	
Turn-off delay time	t _{D(OFF)}		-	14.5	-	
Fall time	t _f		-	3.5	-	
Total gate charge	Q _g	V _{DS} =15V,I _D =6A V _{GS} =10V	-	5.2	-	nC
Gate-source charge	Q _{gs}		-	2.5	-	
Gate-drain charge	Q _{gd}		-	1	-	

Thermal Characteristics

Thermal Resistance junction-to ambient	R _{th JA}	100	°C/W
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N-Channel: Typical Electrical And Thermal Characteristics

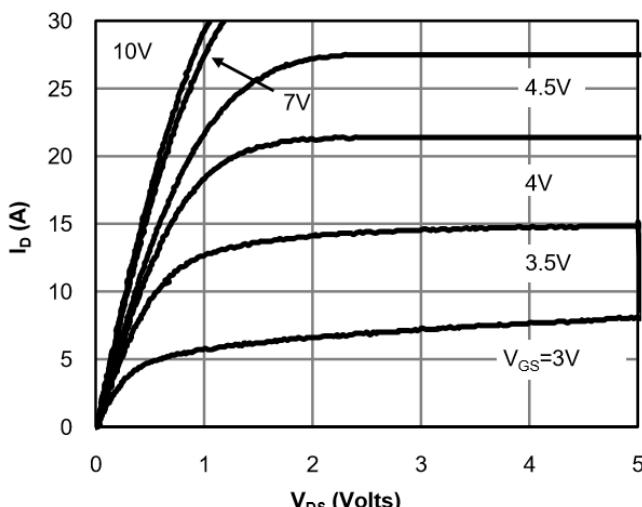


Fig 1: On-Region Characteristics (Note E)

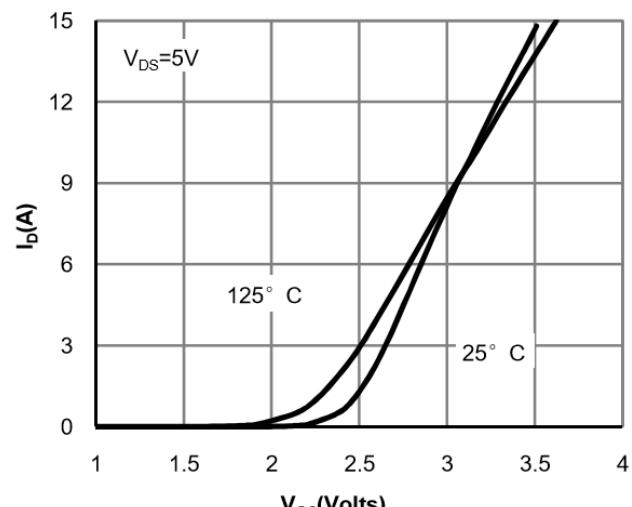


Figure 2: Transfer Characteristics (Note E)

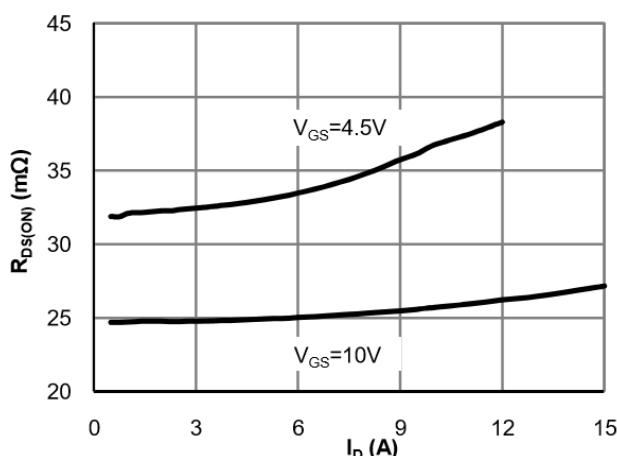


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

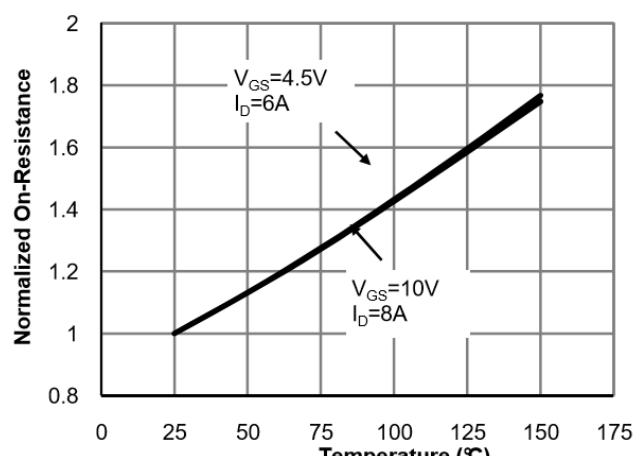


Figure 4: On-Resistance vs. Junction Temperature (Note E)

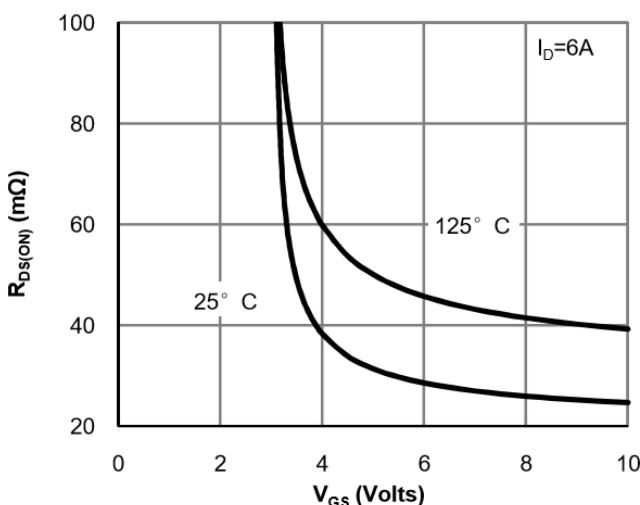


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

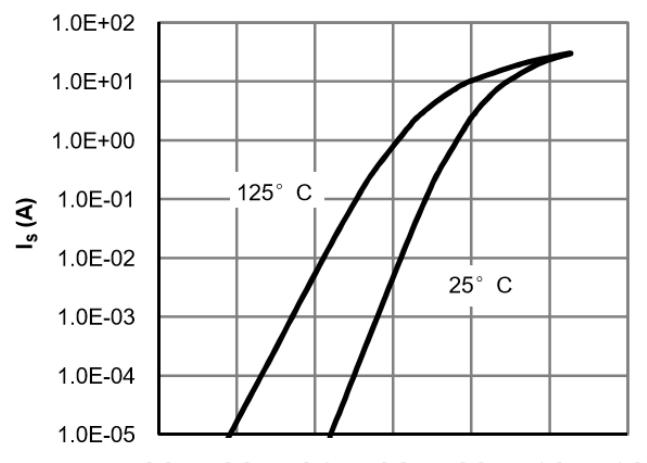
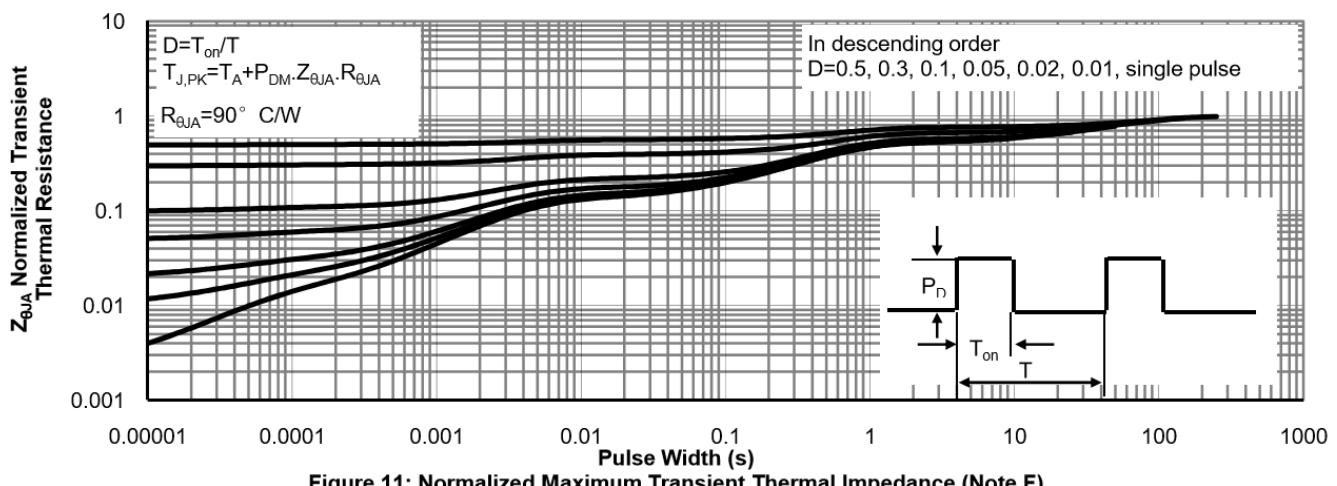
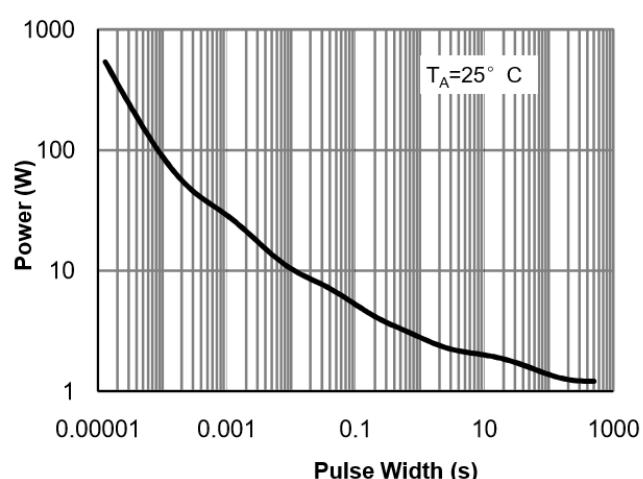
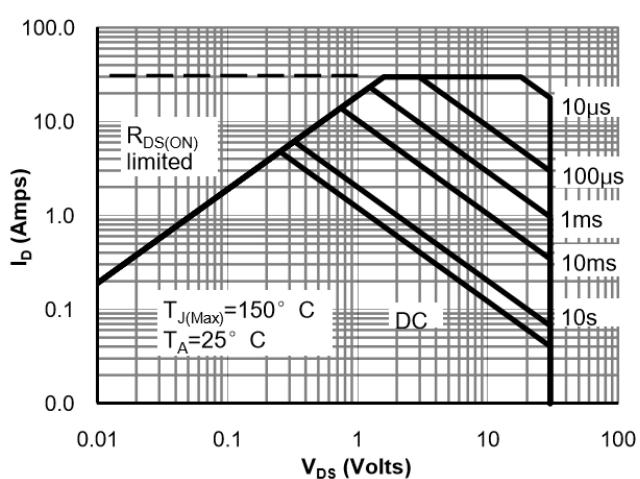
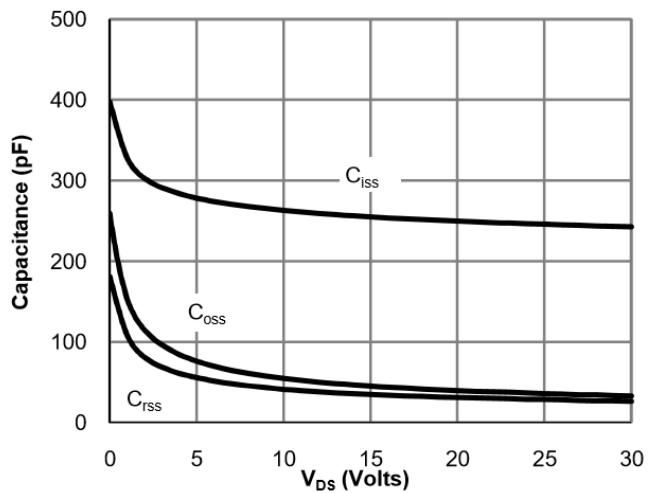
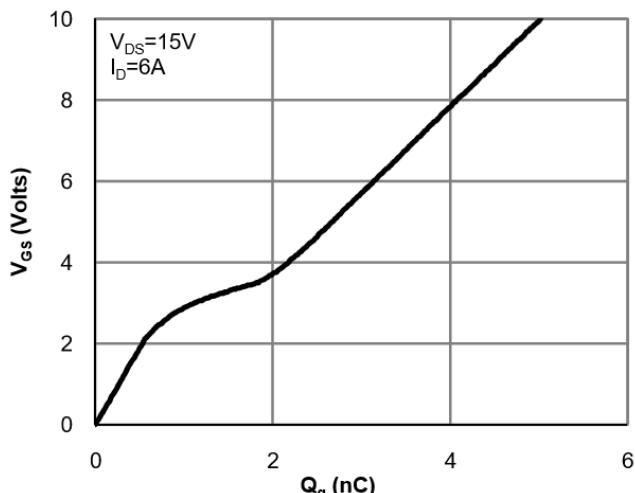
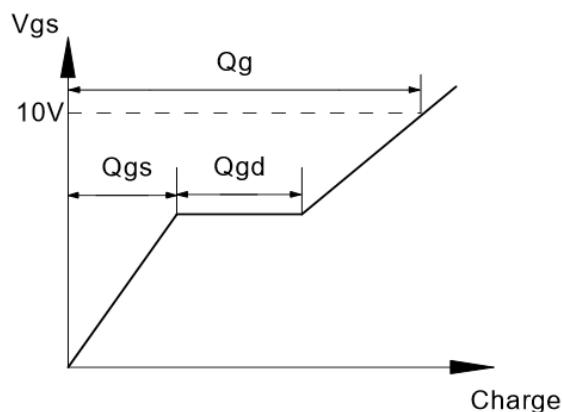
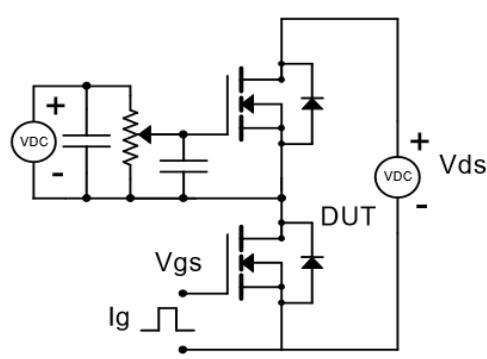


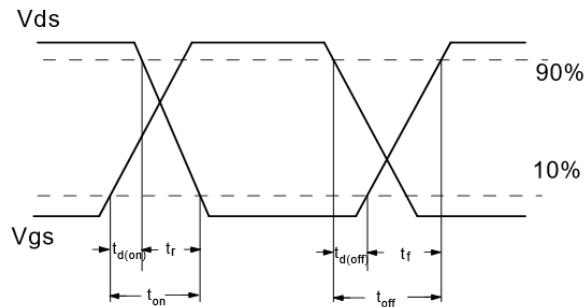
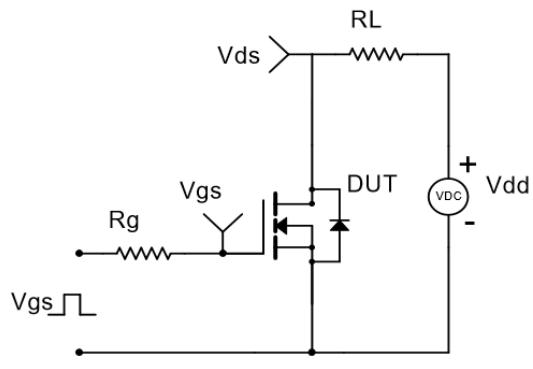
Figure 6: Body-Diode Characteristics (Note E)



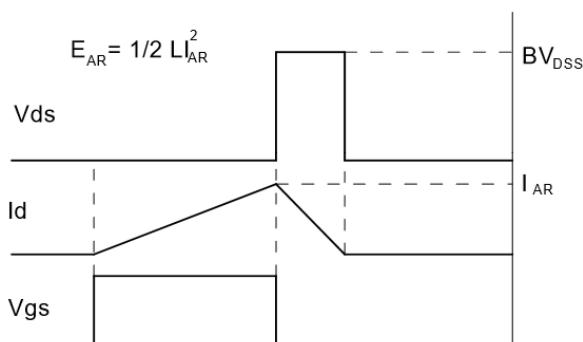
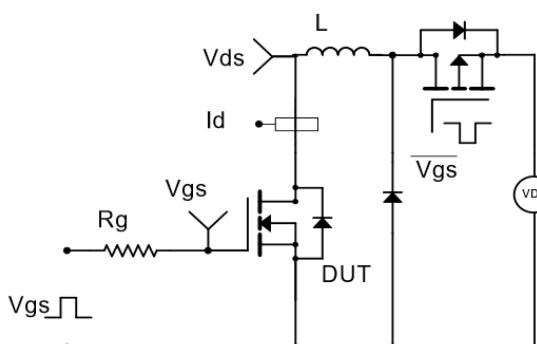
Gate Charge Test Circuit & Waveform



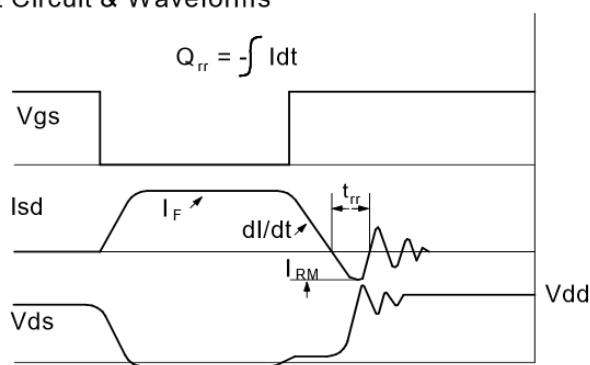
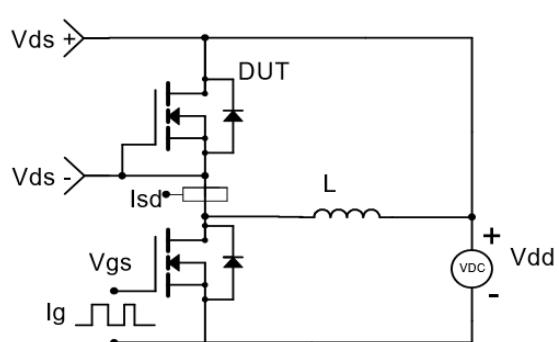
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



P-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF Characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	μA
Gate-body leakage	I_{GSS}	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm20\text{V}$	-	-	±100	nA
ON Characteristics						
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-0.8	-1.32	-2	V
Drain-source on-state resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-6\text{A}$	-	35	45	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-5\text{A}$	-	49	60	
Forward transconductance	g_{fs}	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-6\text{A}$	-	18	-	S
Dynamic Characteristics						
Input capacitance	C_{ISS}	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}$ $f=1.0\text{MHz}$	-	760	-	pF
Output capacitance	C_{OSS}		-	140	-	
Reverse transfer capacitance	C_{RSS}		-	95	-	
Gate resistance	R_g	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}$, $f=1.0\text{MHz}$	-	3.2	5	Ω
Switching Characteristics						
Turn-on delay time	$t_{\text{D}(\text{ON})}$	$V_{\text{DS}}=-15\text{V}$ $V_{\text{GS}}=-10\text{V}$ $R_L=2.3\Omega$ $R_{\text{GEN}}=3\Omega$	-	8	-	ns
Rise time	t_r		-	6	-	
Turn-off delay time	$t_{\text{D}(\text{OFF})}$		-	17	-	
Fall time	t_f		-	5	-	
Total gate charge	Q_g	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-6\text{A}$ $V_{\text{GS}}=-10\text{V}$	-	13.6	-	nC
Gate-source charge	Q_{gs}		-	2.5	-	
Gate-drain charge	Q_{gd}		-	3.2	-	

P-Channel: Typical Electrical And Thermal Characteristics

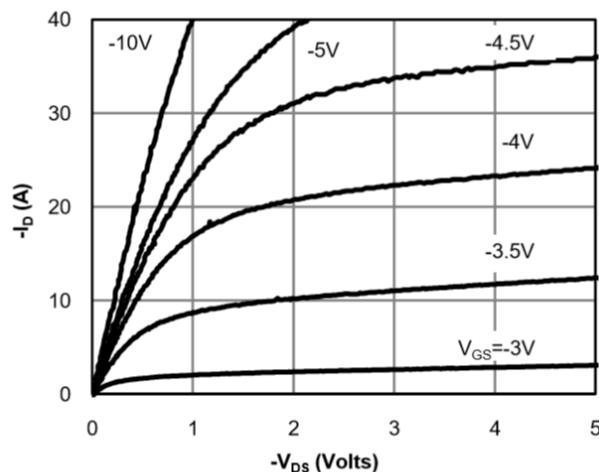


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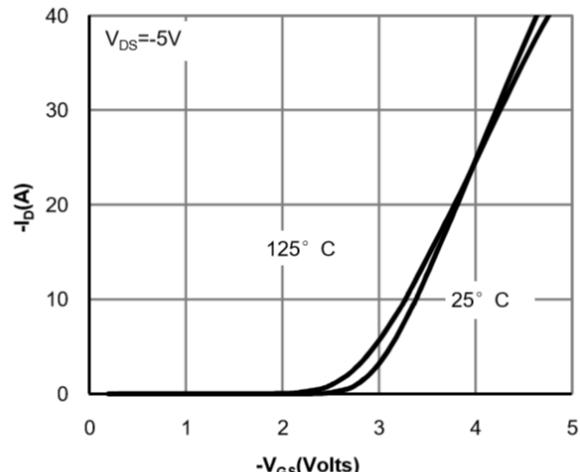


Figure 2: Transfer Characteristics (Note E)

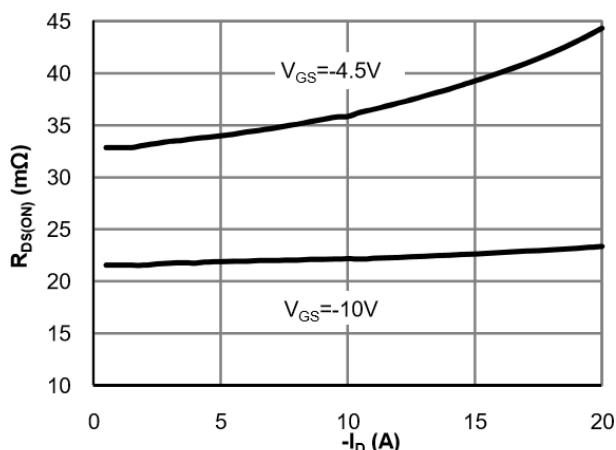


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

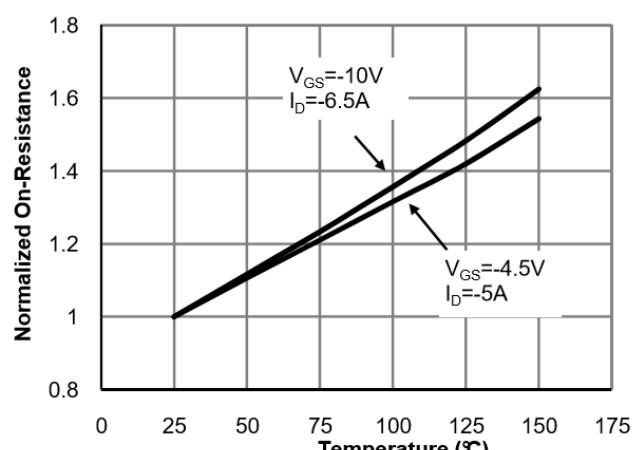


Figure 4: On-Resistance vs. Junction Temperature (Note E)

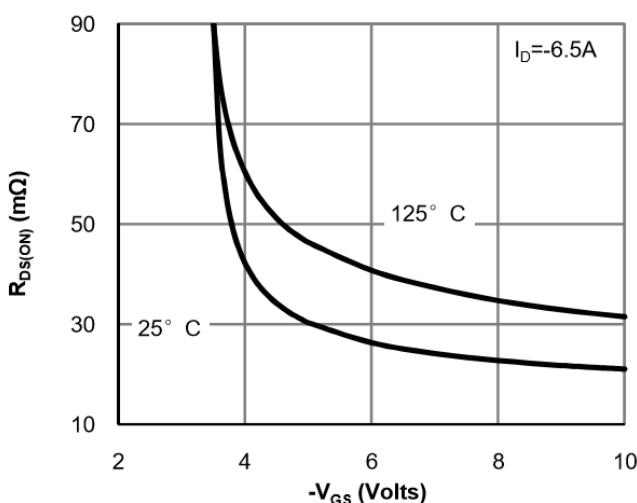


Figure 5: On-Resistance vs. Gate-Source Voltage (Note F)

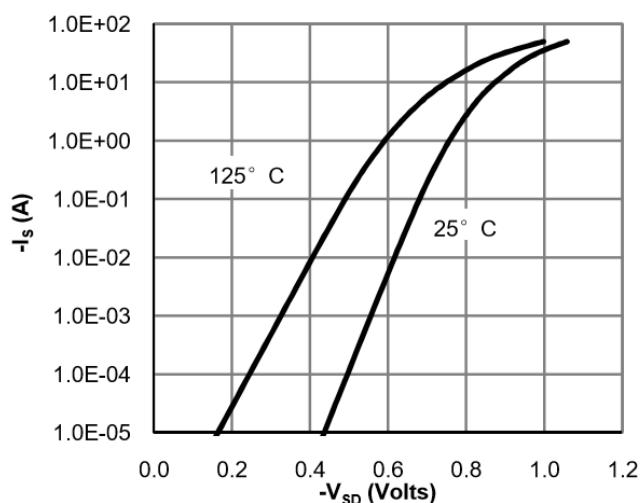
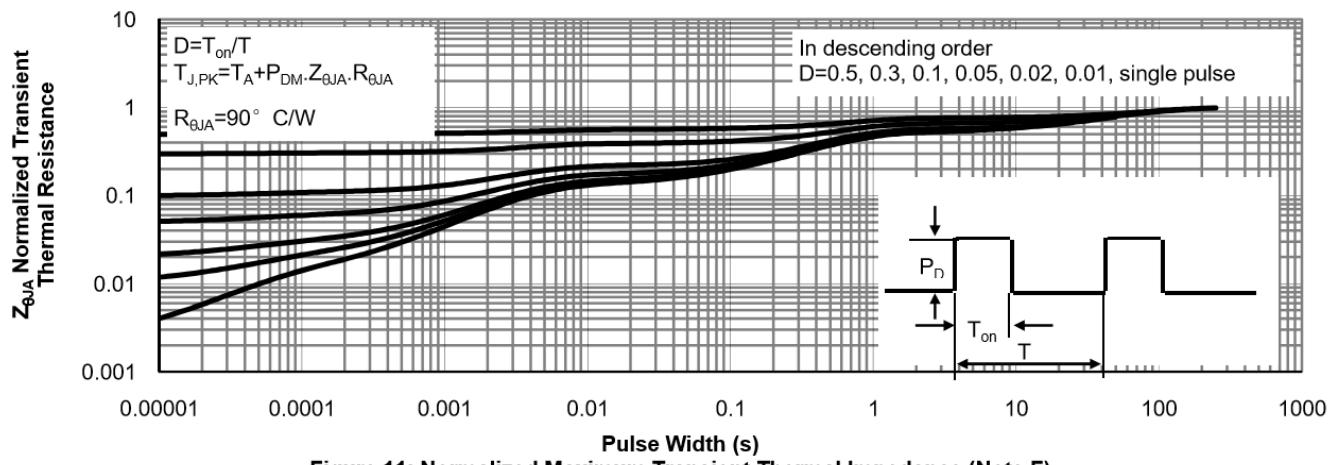
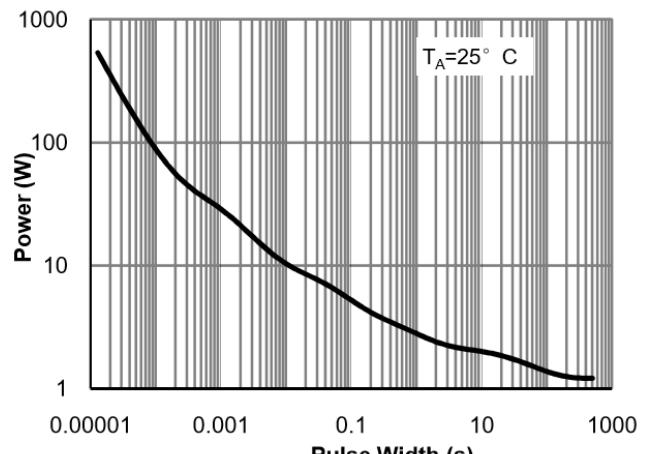
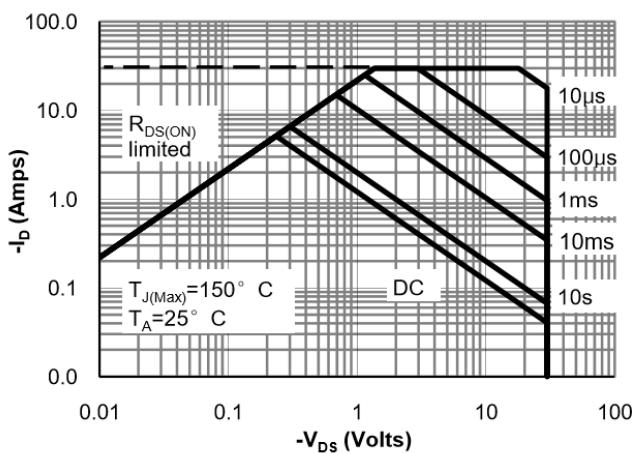
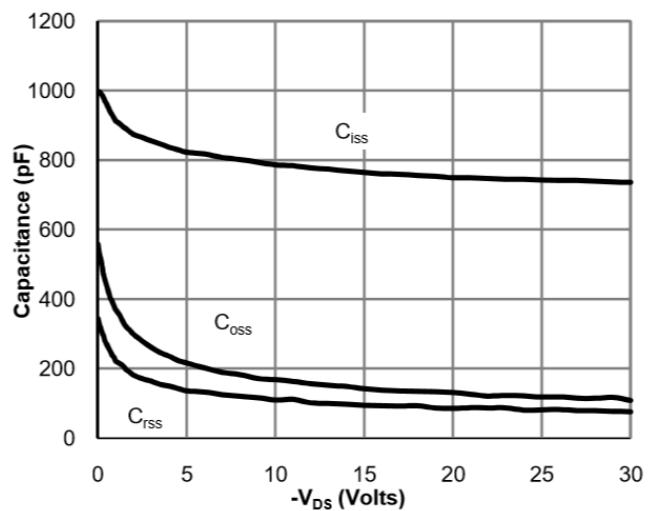
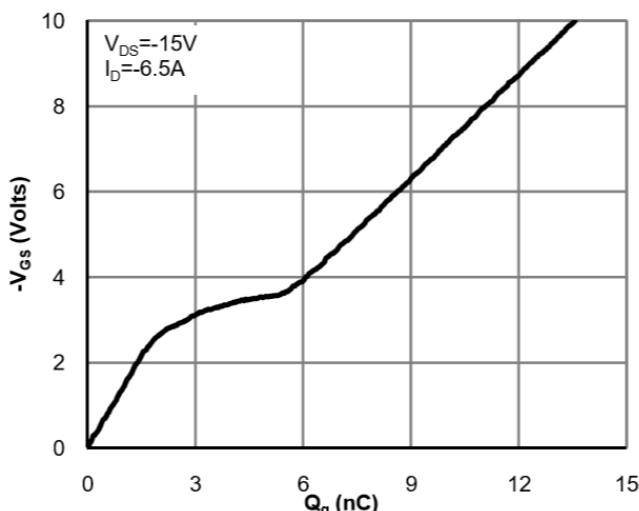
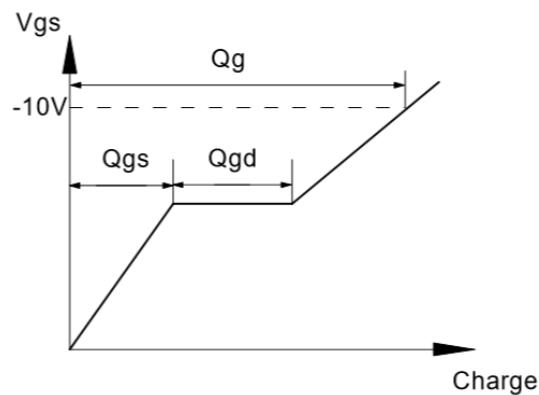
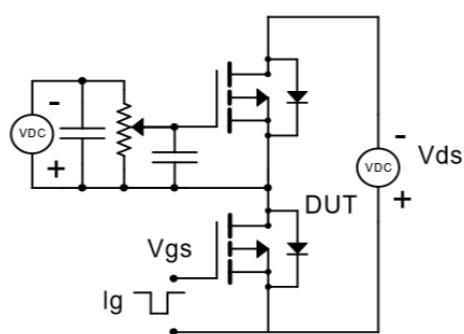


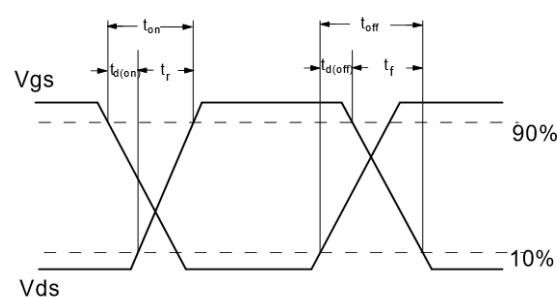
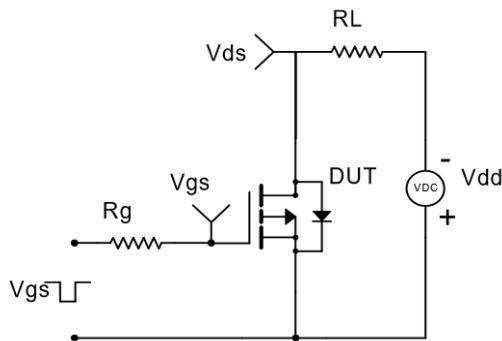
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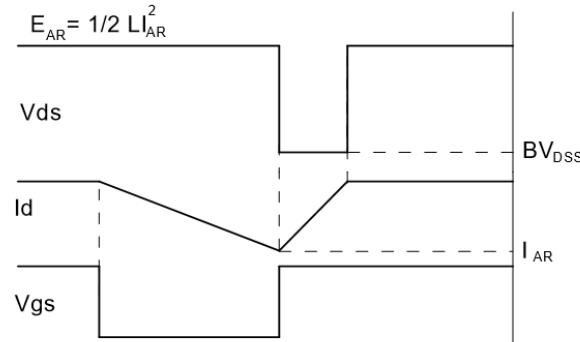
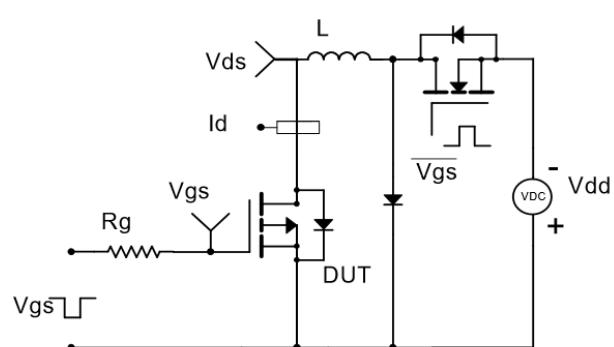
Gate Charge Test Circuit & Waveform



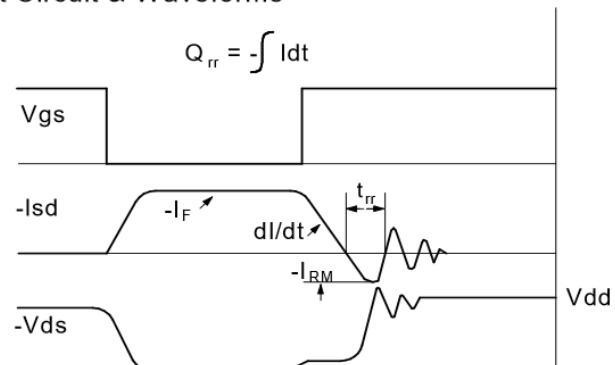
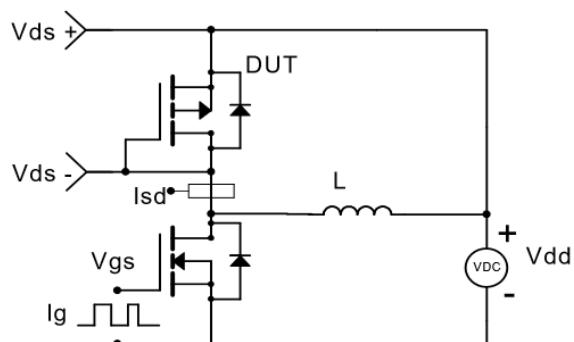
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

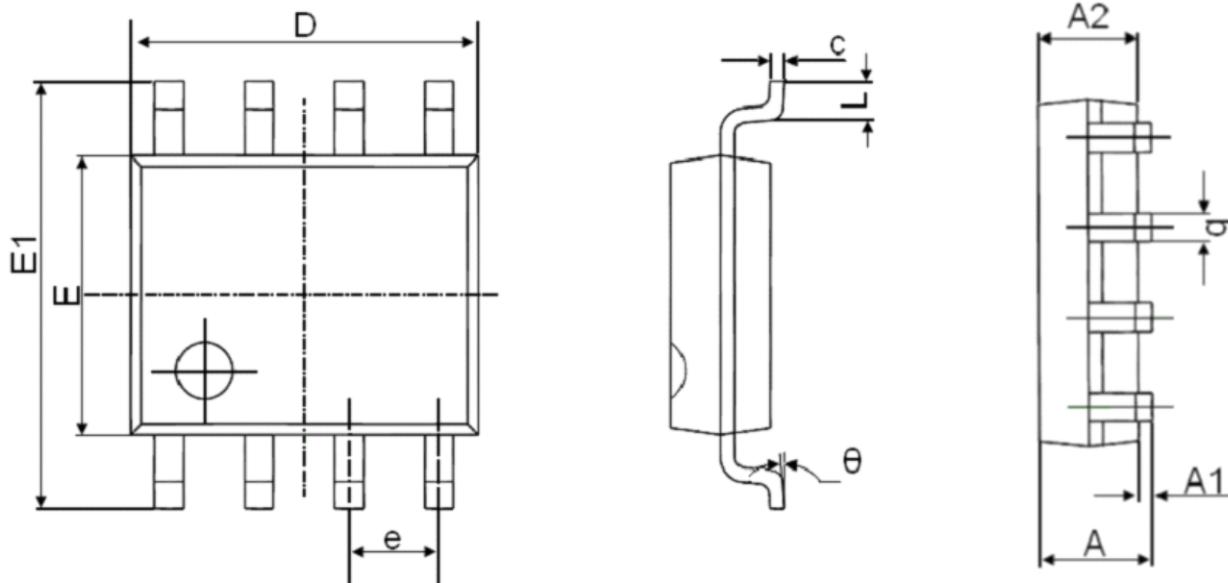


Diode Recovery Test Circuit & Waveforms



Package Information

- SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°